

L Number	Hits	Search Text	DB	Time stamp
10	1	6558239.pn.	USPAT; US-PGPUB; EPO; JPO	2004/08/12 11:10
63	1	"20040106364"	USPAT; US-PGPUB; EPÖ; JPO	2004/08/12 11:37
75	17	5688360.URPN.	USPAT	2004/08/12 11:47
76	98	polishing near2 (station stations) same (cleaning scrubbing) near2 (station stations)	USPAT; US-PGPUB; EPO; JPO	2004/08/12 12:13
-	458	polishing with cleaning with system	USPAT; US-PGPUB; EPO; JPO	2004/08/11 16:48
-	1642	(wafer wafers) and polishing and cleaning and (cylinders cylindrical)	USPAT; US-PGPUB; EPO; JPO	2004/08/11 18:04
-	299	156/345.12.ccls.	USPAT; US-PGPUB; EPO; JPO	2004/08/11 17:01
-	210	451/190.ccls.	USPAT; US-PGPUB; EPO; JPO	2004/08/11 17:03
-	42	("3978580" "4094058" "4653864" "4685180" "4691995" "4775225" "5247377" "5263888" "5379139" "5406989" "5499128" "5507323" "5511591" "5539545" "5548429" "5642214" "5680189" "5742370" "5757451" "5852484" "5854664" "5861932" "5875922" "5952676" "5956112" "6001203" "6011609" "6016178" "6016181" "6055035" "6163357" "6219126" "6226067" "6236445" "6304306" "6304311" "6319100" "6325704" "6337730" "6361867" "6414733" "6565421" "2001/0021000").PN.	USPAT	2004/08/11 17:10
-	389	451/194.ccls.	USPAT; US-PGPUB; EPO; JPO	2004/08/11 17:17
-	403	451/178.ccls.	USPAT; US-PGPUB; EPO; JPO	2004/08/12 11:37
-	421	((wafer wafers) and polishing and cleaning and (cylinders cylindrical)) and 451/\$.ccls.	USPAT; US-PGPUB; EPO; JPO	2004/08/11 18:06